

Product Change Notification - KSRA-20CIED111

Date: 08 Feb 2018
Product Category: 8-bit PIC Microcontrollers; 16-Bit - Microcontrollers and Digital Signal Controllers
Notification subject: CCB 3014 Final Notice: Qualification of CuPdAu bond wire in selected products for 160K wafer technology available in 44L QFN (8x8x0.9mm) package at NSEB assembly site
Notification text: **PCN Status:**
Final notification

PCN Type:
Manufacturing Change

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products for 160K wafer technology available in 44L QFN (8x8x0.9mm) package at NSEB assembly site

Pre Change:

Using gold (Au) bond wire, 8200T or 8600 die attach, G770HCD or G700LTD mold compound material, and C194 or AgCu lead frame material.

Post Change:

Using palladium coated copper with gold flash (CuPdAu) bond wire, 8600 die attach, G700LTD mold compound material, C194 lead frame material.

Pre and Post Change Summary:

	Pre Change		Post Change
Assembly Site	UTAC Thai Limited LTD. / NSEB		UTAC Thai Limited LTD. / NSEB
Wire material	Au Wire		CuPdAu Wire
Die attach material	8200T	8600	8600
Molding compound material	G770HCD	G700LTD	G700LTD
Lead frame material	AgCu	C194	C194

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve manufacturability and qualify CuPdAu bond wire at NSEB assembly site.

Change Implementation Status:

In Progress

Estimated First Ship Date:

March 08, 2018 (date code:1810)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	June 2017					-->	February 2018				March 2018			
	22	23	24	25	26		05	06	07	08	09	10	11	12
Initial PCN Issue Date				X										
Qual Report Availability							X							
Final PCN Issue Date							X							
Estimated Implementation Date											X			

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual Report

Revision History:

June 29, 2017: Issued initial notification.

February 08, 2018: Issued final notification. Attached the Qualification Report. Provided estimated first ship date on March 08, 2018.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

- [PCN_KSRA-20CIED111_Affected CPN.pdf](#)
- [PCN_KSRA-20CIED111_Qual Report.pdf](#)
- [PCN_KSRA-20CIED111_Affected CPN.xlsx](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to change your product/process change notification (PCN) profile please log on to our website at <http://www.microchip.com/PCN> sign into myMICROCHIP to open the myMICROCHIP home page, then select a profile option from the left navigation bar.

To opt out of future offer or information emails (other than product change notification emails), click here to go to [microchipDIRECT](#) and login, then click on the "My account" link, click on "Update profile" and un-check the box that states "Future offers or information about Microchip's products or services."

PCN_KSRA-20CIED111-CCB 3014 Final Notice: Qualification of CuPdAu bond wire in selected products for 160K wafer technology available in 44L QFN (8x8x0.9mm) package at NSEB assembly site

Affected Catalog Part Numbers (CPN)

PCN_KSRA-20CIED111
CATALOG_PART_NBR
DSPIC30F2023-20E/ML
DSPIC30F2023-30I/ML
DSPIC30F2023T-30I/ML
DSPIC30F2023T-30V/MLD31
DSPIC30F3010-20I/ML
DSPIC30F3010-30I/ML
DSPIC30F3010T-30I/ML
DSPIC30F3011-10I/MLB24
DSPIC30F3011-20E/ML
DSPIC30F3011-20I/ML
DSPIC30F3011-30I/ML
DSPIC30F3011T-10I/MLB21
DSPIC30F3012-20E/ML
DSPIC30F3012-20I/ML
DSPIC30F3012-30I/ML
DSPIC30F3012T-20I/ML
DSPIC30F3013-20E/ML
DSPIC30F3013-20I/ML
DSPIC30F3013-30I/ML
DSPIC30F3013-30I/MLB31
DSPIC30F3013T-20I/ML
DSPIC30F3013T-30I/ML
DSPIC30F3013T-30I/MLB31
DSPIC30F3014-20E/ML
DSPIC30F3014-20I/ML
DSPIC30F3014-30I/ML
DSPIC30F3014-30I/MLA31
DSPIC30F3014T-30I/MLA31
DSPIC30F4011-20E/ML
DSPIC30F4011-20I/ML
DSPIC30F4011-30I/ML
DSPIC30F4012-20E/ML
DSPIC30F4012-20I/ML
DSPIC30F4012-30I/ML
DSPIC30F4013-20E/ML
DSPIC30F4013-20I/ML
DSPIC30F4013-30I/ML
DSPIC30F4013-30I/MLB31
DSPIC30F4013T-30I/ML
DSPIC30F4013T-30I/MLB31
PIC16F884-E/ML
PIC16F884-I/ML
PIC16F884T-I/ML

PCN_KSRA-20CIED111-CCB 3014 Final Notice: Qualification of CuPdAu bond wire in selected products for 160K wafer technology available in 44L QFN (8x8x0.9mm) package at NSEB assembly site

Affected Catalog Part Numbers (CPN)

PCN_KSRA-20CIED111
CATALOG_PART_NBR
PIC16F887-E/ML
PIC16F887-I/ML
PIC16F887T-I/ML
PIC16F914-E/ML
PIC16F914-I/ML
PIC16F914T-I/ML
PIC16F917-E/ML
PIC16F917-I/ML
PIC16F917T-I/ML
PIC18F4221-E/ML
PIC18F4221-I/ML
PIC18F4321-E/ML
PIC18F4321-I/ML
PIC18F4410-E/ML
PIC18F4410-I/ML
PIC18F4420-E/ML
PIC18F4420-I/ML
PIC18F4420T-I/ML
PIC18F4423-E/ML
PIC18F4423-I/ML
PIC18F4423T-I/ML
PIC18F4450-I/ML
PIC18F4455-I/ML
PIC18F4455T-I/ML
PIC18F4458-I/ML
PIC18F4480-E/ML
PIC18F4480-I/ML
PIC18F4480T-I/ML
PIC18F4510-E/ML
PIC18F4510-I/ML
PIC18F4510T-I/ML
PIC18F4515-I/ML
PIC18F4520-E/ML
PIC18F4520-I/ML
PIC18F4520T-E/ML
PIC18F4520T-I/ML
PIC18F4523-E/ML
PIC18F4523-I/ML
PIC18F4523T-I/ML
PIC18F4525-E/ML
PIC18F4525-I/ML
PIC18F4525T-I/ML
PIC18F4550-I/ML

PCN_KSRA-20CIED111-CCB 3014 Final Notice: Qualification of CuPdAu bond wire in selected products for 160K wafer technology available in 44L QFN (8x8x0.9mm) package at NSEB assembly site

Affected Catalog Part Numbers (CPN)

PCN_KSRA-20CIED111
CATALOG_PART_NBR
PIC18F4550T-I/ML
PIC18F4553-I/ML
PIC18F4580-E/ML
PIC18F4580-I/ML
PIC18F4580T-I/ML
PIC18F4585-E/ML
PIC18F4585-H/ML
PIC18F4585-I/ML
PIC18F4585-I/MLC01
PIC18F4585T-I/ML
PIC18F4610-I/ML
PIC18F4620-E/ML
PIC18F4620-I/ML
PIC18F4620T-I/ML
PIC18F4680-E/ML
PIC18F4680-H/ML
PIC18F4680-I/ML
PIC18F4680T-I/ML
PIC18F4682-E/ML
PIC18F4682-I/ML
PIC18F4685-E/ML
PIC18F4685-I/ML
PIC18F4685T-I/ML
PIC18LF4221-I/ML
PIC18LF4221T-I/ML
PIC18LF4321-I/ML
PIC18LF4410-I/ML
PIC18LF4420-I/ML
PIC18LF4420T-I/ML
PIC18LF4423-I/ML
PIC18LF4423T-I/ML
PIC18LF4450-I/ML
PIC18LF4450T-I/ML
PIC18LF4455-I/ML
PIC18LF4455T-I/ML
PIC18LF4458-I/ML
PIC18LF4480-I/ML
PIC18LF4480T-I/ML
PIC18LF4510-I/ML
PIC18LF4510T-I/ML
PIC18LF4515-I/ML
PIC18LF4520-I/ML
PIC18LF4520T-I/ML

PCN_KSRA-20CIED111-CCB 3014 Final Notice: Qualification of CuPdAu bond wire in selected products for 160K wafer technology available in 44L QFN (8x8x0.9mm) package at NSEB assembly site

Affected Catalog Part Numbers (CPN)

PCN_KSRA-20CIED111
CATALOG_PART_NBR
PIC18LF4523-I/ML
PIC18LF4523T-I/ML
PIC18LF4525-I/ML
PIC18LF4525T-I/ML
PIC18LF4550-I/ML
PIC18LF4550T-I/ML
PIC18LF4553-I/ML
PIC18LF4580-I/ML
PIC18LF4585-I/ML
PIC18LF4585T-I/ML
PIC18LF4610-I/ML
PIC18LF4620-I/ML
PIC18LF4620-I/ML035
PIC18LF4620T-I/ML
PIC18LF4620T-I/ML035
PIC18LF4680-I/ML
PIC18LF4682-I/ML
PIC18LF4685-I/ML
PIC18LF4685T-I/ML